



Material Content Data Sheet



Sales Product Name		BTT6010-1EKB		Issued		12. November 2015		
MA#		MA001390614						
Package		PG-DSO-14-47		Weight*		151.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.709	3.12	3.12	31180	31180
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		114	
	non noble metal	zinc	7440-66-6	0.069	0.05		458	
	non noble metal	iron	7439-89-6	1.383	0.92		9160	
wire	non noble metal	copper	7440-50-8	56.175	37.19	38.17	371929	381661
	non noble metal	copper	7440-50-8	0.760	0.50	0.50	5033	5033
	encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1094
encapsulation	plastics	epoxy resin	-	7.603	5.03		50342	
	inorganic material	silicondioxide	60676-86-0	74.878	49.58	54.72	495758	547194
leadfinish	non noble metal	tin	7440-31-5	2.503	1.66	1.66	16569	16569
plating	noble metal	silver	7440-22-4	1.470	0.97	0.97	9735	9735
glue	plastics	epoxy resin	-	0.228	0.15		1510	
	noble metal	silver	7440-22-4	1.075	0.71	0.86	7118	8628
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com